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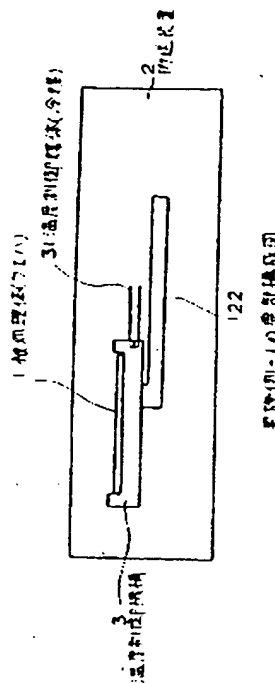
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TITLE : METHOD AND APPARATUS FOR
TREATING UNTREATED OBJECT



ABSTRACT : PURPOSE: To prevent nonuniformity in an untreated object and irregularity of treatment between untreated objects when two or more processes are performed under mutually different temperature conditions, by equipping a conveying equipment with a temperature controlling mechanism for untreated objects.

CONSTITUTION: In a conveying system for carrying an untreated objects (wafer) 1 from a high temperature process (CVD) to a low temperature process (etching), a cooling equipment is installed at the bottom part of a wafer mounting part of a conveying equipment 22 as a means for retaining and carrying the untreated objects. The whole part of the wafer mounting part constitutes a temperature controlling means 3, and controls the temperature by making refrigerant (temperature controlling medium) 31 flow in the mechanism 3 while the wafer is carried from the high temperature process to the low temperature process. That is, by equipping the equipment 2 with the cooling equipment as the mechanism 3, the surfacial uniformity and the stability of etching rate can be improved. Hence, when two or more processes are performed under mutually different temperature conditions, nonuniformed in the untreated objects and irregularity of treatment between the untreated objects can be prevented.

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